506676106 05/21/2021

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KAZUHIRO YAMAMOTO	05/14/2021
KYUNG HO LEE	05/14/2021

RECEIVING PARTY DATA

Name:	HOSIDEN CORPORATION	
Street Address:	4-33, KITAKYUHOJI 1-CHOME	
City:	YAO-SHI, OSAKA	
State/Country:	JAPAN	
Postal Code:	581-0071	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17326758

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 5150-064

NAME OF SUBMITTER: LEONARD D. BOWERSOX

SIGNATURE: /Leonard D. Bowersox/

DATE SIGNED: 05/21/2021

Total Attachments: 2

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PATENT 506676106 REEL: 056313 FRAME: 0433

ASSIGNMENT

WHEREAS We, the below named inventors [hereinafter collectively referred to as Assignors], have made an invention entitled: CAPACITIVE SENSOR, for which We filed an application for United States Letters Patent on May 21, 2021, as Application No. 17/326,758 (the Assignee being hereby authorized to insert the filing date and the Patent Application No. when ascertained); and

WHEREAS, <u>HOSIDEN CORPORATION</u>, a corporation registered in <u>Japan</u>. [hereinafter referred to as Assignee], whose post office address is <u>4-33</u>, <u>Kitakyuhoji 1-chome</u>, <u>Yao-shi</u>, <u>Osaka 581-0071</u>, <u>Japan</u>, is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that for good and valuable consideration, the receipt of which from assignee is hereby acknowledged, We, as assignors, have sold, assigned, transferred, and set over unto the assignee, its lawful successors, and assigns, our entire right, title, and interest in and to this invention and this non-provisional application, and all divisions, and continuations thereof, and all Letters Patents of the United States that may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such application, and all applications for Letters Patents which may hereafter be filed for this invention in any foreign country and all Letters Patents which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patents for this invention to assignee, its successors, and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that We have the full right to convey the interest assigned by this Assignment, and We have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that We will, without further consideration, communicate with assignee, its successors, and assigns, any facts known to us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors, and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors, and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors, and assigns.

FULL NAME OF FIRST INVENTOR: Kazuhiro YAMAMOTO

Address: e/o HOSIDEN CORPORATION, 4-33, Kitakyuhoji 1-chome, Yao-shi, Osaka 581-0071, Japan

Signature: Kazuhiro YAMAMOTO

Date: May 14, 2021

FULL NAME OF SECOND INVENTOR: Kyung Ho LEE

Address: c/o HOSIDEN CORPORATION, 4-33, Kitakyuhoji 1-chome, Yao-shi, Osaka 581-0071, Japan

Signature: Kyungho LEE

Date: May 14, 2021